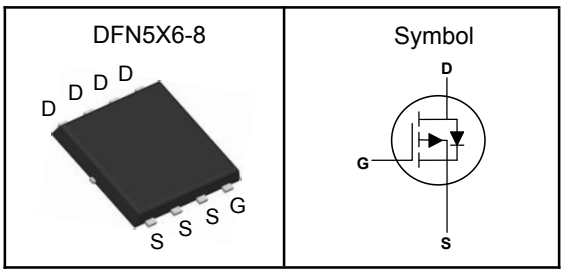
P-Channel Enhancement Mode MOSFET

Features

- Low Rdson for low conduction loss
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Pin Description



Applications

- Power Management in Desktop Computer
- DC/DC Converters

V_{DSS}	-60	V
$R_{DS(ON)-Typ}$	8.5	mΩ
I_D	-70	A

Absolute Maximum Ratings (T_C=25℃, Unless Otherwise Noted)

Symbol	Parameter		P-Channel	Unit
V_{DSS}	Drain-Source Voltage		-60	V
V_{GSS}	Gate-Source Voltage		±20	V
T_J	Maximum Junction Temperature		-55 to 150	℃
T_{STG}	Storage Temperature Range		-55 to 150	℃
I_{DM} ①	Pulse Drain Current Tested	T_C=25°C	-280	A
I_D	Continuous Drain Current	T_C=25°C	-70	A
P_D	Maximum Power Dissipation	T_C=25°C	133	W
EAS	Single Pulse Avalanche Energy	L=0.1mH	320	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$ ③	Thermal Resistance-Junction to Ambient Steady State	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction-Case Steady State	0.88	℃/W

Note ①: Max. current is limited by bonding wire.

Note ②: UIS tested and pulse width are limited by maximum junction temperature 150℃.

Note ③: Surface Mounted on 1in² FR-4 board with 1oz.

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Electrical Characteristics (T_J=25℃, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=-250uA	-60	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=-60V, V_{GS}=0V	---	---	-1	uA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=-250uA	-1.1	---	-2.5	V
I_{GSS}	Gate Leakage Current	V_{GS}=±25V, V_{DS}=0V	---	---	±100	nA
$R_{DS(ON)}$	Drain-Source On-state Resistance	V_{GS}=-10V, I_D=-20A	---	8.5	10.5	mΩ
		V_{GS}=-4.5V, I_D=-10A	---	11	14	mΩ
Dynamic Characteristics⑤						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=-25V, Freq.=1MHz	---	8560	---	pF
C_{oss}	Output Capacitance		---	480	---	
C_{rss}	Reverse Transfer Capacitance		---	425	---	
$T_{d(on)}$	Turn-on Delay Time	V_{DD}=-48V , V_{GS}=-10V , R_G=6Ω, I_D=-1A,	---	70	---	nS
T_r	Turn-on Rise Time		---	205	---	
$T_{d(off)}$	Turn-off Delay Time		---	400	---	
T_f	Turn-off Fall Time		---	190	---	
Q_g	Total Gate Charge	V_{DS}=-48V , V_{GS}=-10V, I_D=-5A	---	140	---	nC
Q_{gs}	Gate-Source Charge		---	17	---	
Q_{gd}	Gate-Drain Charge		---	28	---	
Source-Drain Characteristics （T_J=25℃）						
V_{SD}④	Diode Forward Voltage	V_{GS}=0V , I_S=-1A , T_J=25℃	---	-0.8	-1.2	V
t_{rr}	Reverse Recovery Time	I_F=-10A , di/dt=100A/μs，T_J=25℃	---	60	---	nS
Q_{rr}	Reverse Recovery Charge		---	60	---	nC

Note ④： Pulse test (pulse width 300us, duty cycle 2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

Typical Characteristics

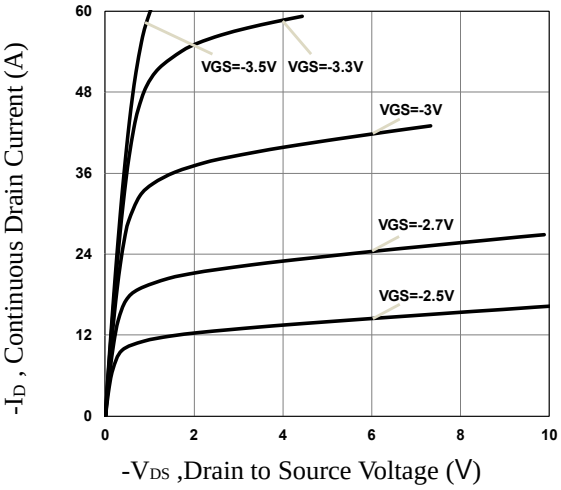


Fig.1 Typical Output Characteristics

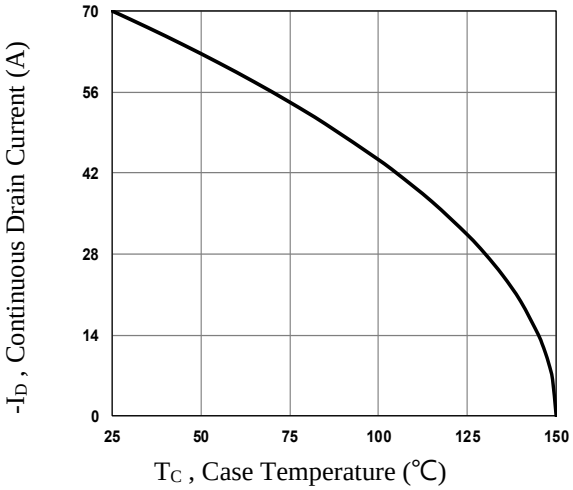


Fig.2 Continuous Drain Current vs. T_C

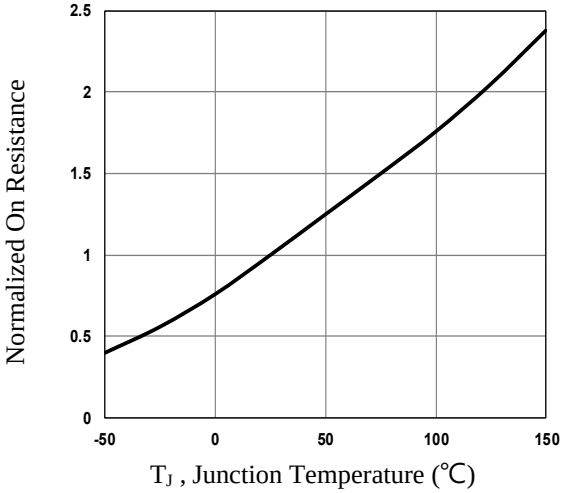


Fig.3 Normalized RDSON vs. T_J

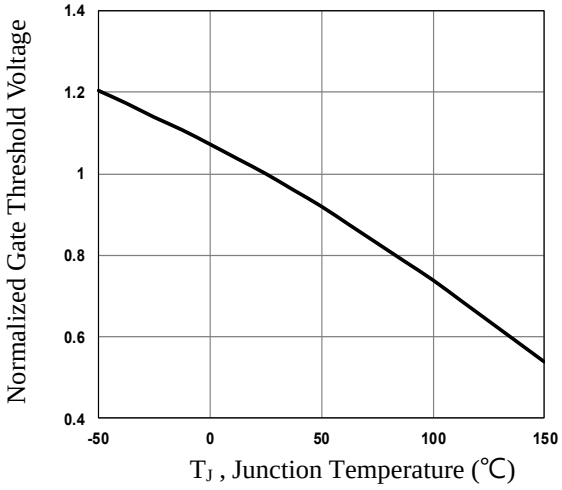


Fig.4 Normalized V_{th} vs. T_J

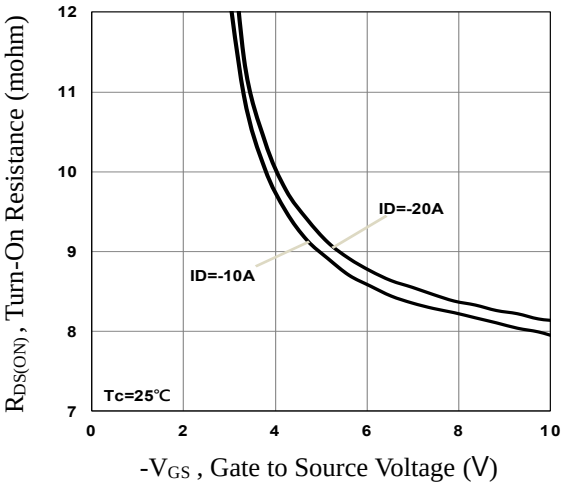


Fig.5 Turn-On Resistance vs. V_{GS}

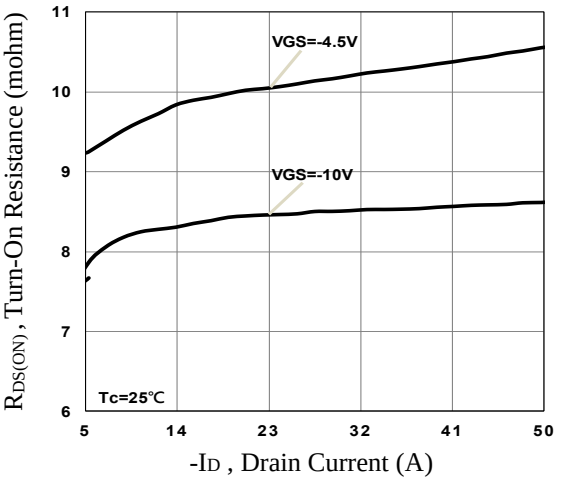


Fig.6 Turn-On Resistance vs. ID

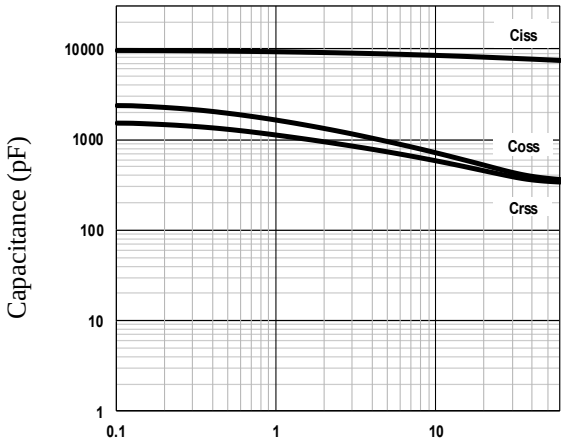


Fig.7 Capacitance Characteristics

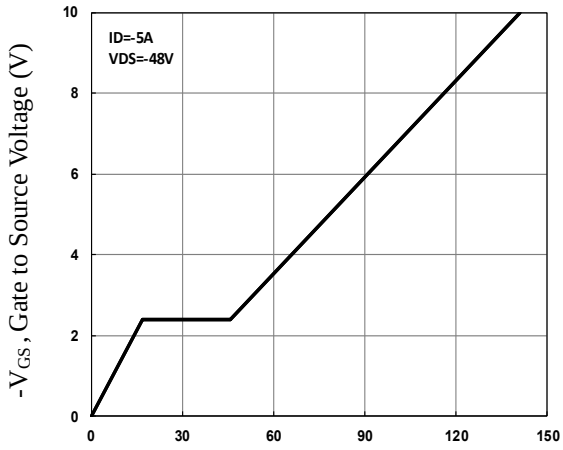


Fig.8 Gate Charge Characteristics

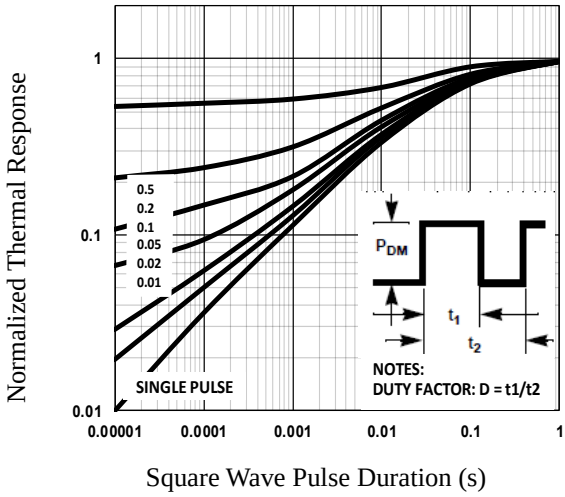


Fig.9 Normalized Transient Impedance

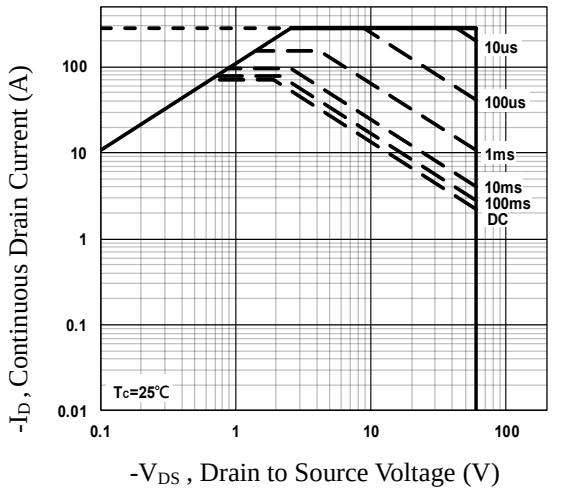


Fig.10 Maximum Safe Operation Area

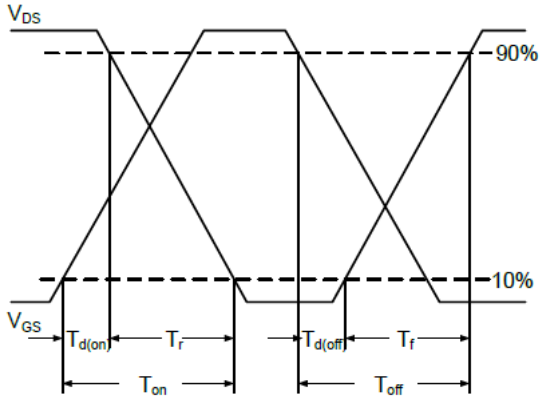


Fig.11 Switching Time Waveform

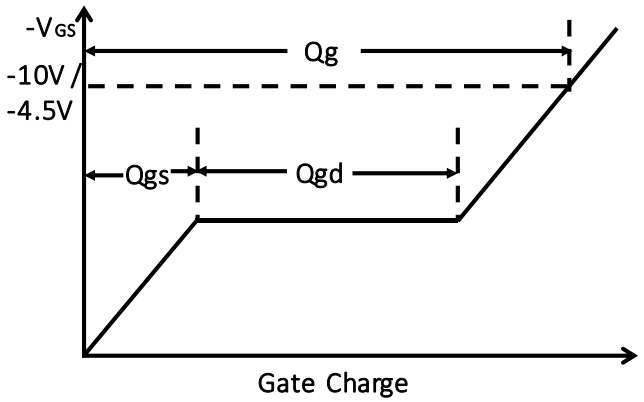
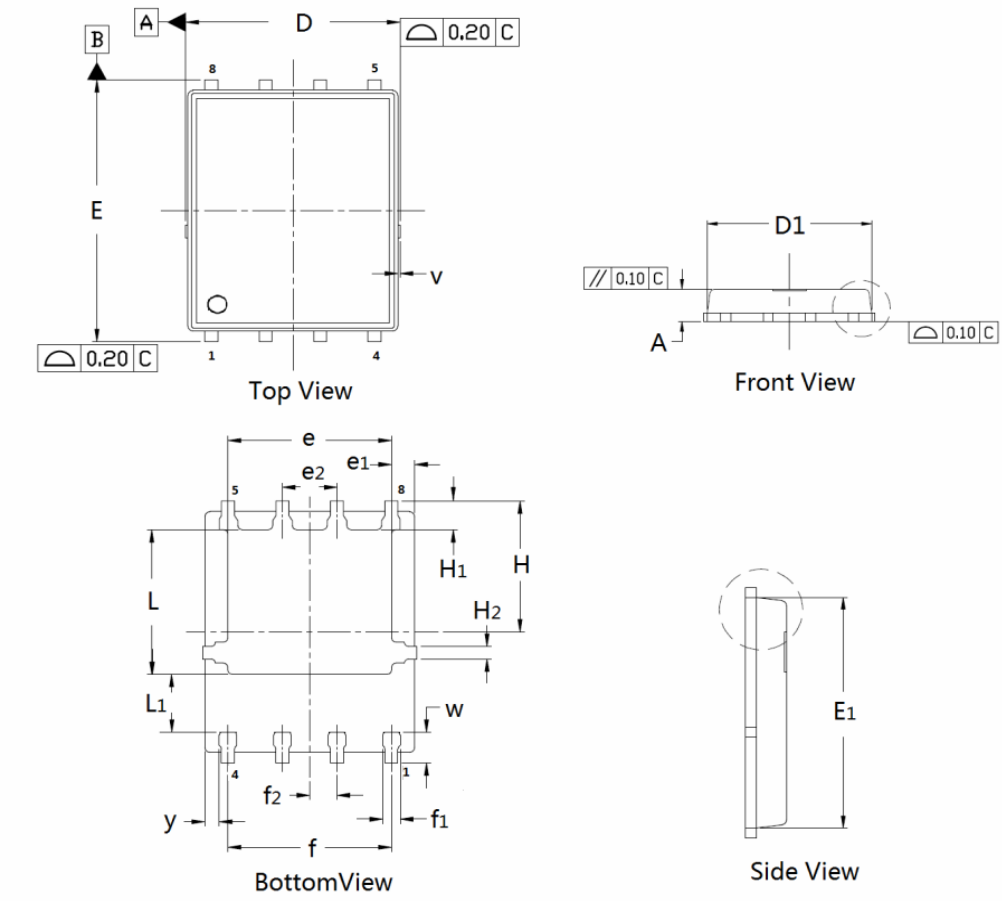


Fig.12 Gate Charge Waveform

DFN5×6 Package Outline Data



DIMENSIONS (unit : mm)

Symbol		Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.02	1.10	**D**	4.90	4.98	5.10
D_1	4.80	4.89	5.10	**E**	5.90	6.11	6.25
E_1	5.65	5.74	5.95	**e**	3.72	3.80	3.92
e_1	--	0.5	--	**e_2**	--	1.	--
f	--	3.8	--	**f_1**	0.31	0.37	0.51
f_2	--	0.6	--	**H**	--	3.	--
H_1	0.59	0.63	0.79	**H_2**	0.26	0.28	0.32
L	3.35	3.45	3.65	**L_1**	--	1.	--
v	--	0.1	--	**w**	0.64	0.68	0.84
y	--	0.3	--		--		--